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Amendments to the Claims:

This listing of claims will replace all prior versions and listing of claims in the application.

Listing of Claims:

1. (CURRENTLY AMENDED) A method for producing a Group III nitride GaN crystal comprising:

growing a crystal in a nitrogen-containing atmosphere by reacting at least one Group III element selected from Ga, Al, and In with nitrogen in a melt that includes Ga, nitrogen and [[a]] flux components including an alkali metal,

wherein the flux further includes Mg the flux components are Na and Mg,
the melt is formed by heating Ga, Mg and purified Na in a nitrogen-containing
atmosphere, and

a proportion of Mg in a sum of Na and Mg is in a range of 0.1 to 5 mol%.

- (CURRENTLY AMENDED) The method according to claim 1, wherein Mg of the flux melt functions as at least one of a flux component and a doping component.
- 3. (CURRENTLY AMENDED) The method according to claim 1, wherein the flux melt includes as a doping component at least one selected from an alkaline-earth metal and Zn.
- 4. (ORIGINAL) The method according to claim 1, wherein the nitrogen is supplied as a nitrogen-containing gas.
- 5. (ORIGINAL) The method according to claim 3, wherein the alkaline-earth metal is at least one selected from Ca, Be, Sr, and Ba.
- 6-8. (CANCELED)

App. No. 10/584,725 Office Action Dated April 14, 2008

9. (CURRENTLY AMENDED) A Group III nitride GaN crystal produced by the method according to claim 1, the GaN crystal containing Mg and at least one of Ca and Zn, wherein a doping amount of Mg is more than 0 and not more than 1 x 10²⁰ cm⁻³.

10-11. (CANCELED)

- 12. (CURRENTLY AMENDED) The Group III nitride GaN crystal according to claim 9, wherein an oxygen concentration of the crystal is 0 to 1×10^{17} cm⁻³.
- 13. (CURRENTLY AMENDED) The Group III-nitride GaN crystal according to claim 9, wherein a resistivity (specific resistance) is not less than $1 \times 10^3 \ \Omega$ -cm.
- 14. (CURRENTLY AMENDED) The Group III nitride GaN crystal according to claim 9, wherein a resistivity (specific resistance) is not less than $1 \times 10^5 \ \Omega \cdot \text{cm}$.
- 15. (CURRENTLY AMENDED) A Group III nitride GaN substrate comprising the Group III nitride GaN crystal according to claim 9.
- 16. (CURRENTLY AMENDED) The Group III nitride GaN substrate according to claim 15, wherein the substrate is a p-type substrate or a semi-insulating substrate.
- 17. (CURRENTLY AMENDED) A field-effect transistor comprising the Group III nitride GaN substrate according to claim 16.
- 18. (NEW) The method according to claim 1, wherein the purified Na is Na having a purity of 99.99%
- 19. (NEW) The method according to claim 1, wherein the melt includes as a doping component at least one of Ca and Zn.